Electronic Patent Application Fee Transmittal							
Application Number:	10	10773968					
Filing Date:	06-	06-Feb-2004					
Title of Invention:	Device and method for forming improved resist layer						
First Named Inventor/Applicant Name:	Pai	Paul D. Shirley					
Filer:	Joh	John Reed/Theresa Oldfield					
Attorney Docket Number:	MIO 0112 PA/40509.272						
Filed as Large Entity							
Utility under 35 USC 111(a) Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:			1				
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Notice of appeal		1401	1	540	540		
Post-Allowance-and-Post-Issuance:			'				
Extension of Times							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			540